



Selective Electroless Plating Process

Apply Selective Plating Primer

With custom masking fixture, spray plating primer onto part per customer masking requirements. The plating primer is cured.

Electroless Plating Process

The Electroless plating process consists of a series of tanks where the parts are immersed to apply Copper and then Nickel. The time in the Copper and Nickel tanks determine the plating thickness. In the selective plating process, a plating primer is applied onto the areas of the part that are to be plated. Areas without the plating primer will maintain molded-in color and texture.

Cybershield engineers work with the customer to define the plating thickness to meet the customer requirements. Copper thickness is defined to meet the resistivity requirement, and the Nickel to meet mechanical abrasion and environmental requirements. Tin is an alternative to Nickel for customer soldering operations.

- Load parts with cured plating basecoat into custom plating fixtures
- Water rinse
- Copper: Electroless Copper – Thickness to customer requirement
- Water rinse
- Nickel: Electroless or Tin - Thickness: customer requirement
- Water rinse
- Post plating cure

Inspect Plated Parts

- Measure metal thickness
- Measure surface resistivity
- Measure adhesion using ASTM 3359 Test Method
- Measure plating pattern versus customer print

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